RECYCLING OF A WAFER COMPRISING A BUFFER LAYER AFTER HAVING SEPARATED A THIN LAYER THEREFROM BY MECHANICAL MEANS INVENTORS: Bruno GHYSELEN, et al. ATTORNEY DOCKET NO. 4717-8600; CUSTOMER NO. 28765

REPLACEMENT DRAWING SHEET





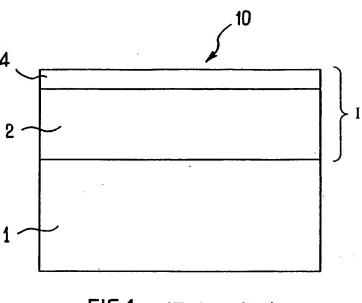


FIG.1 (Prior Art)

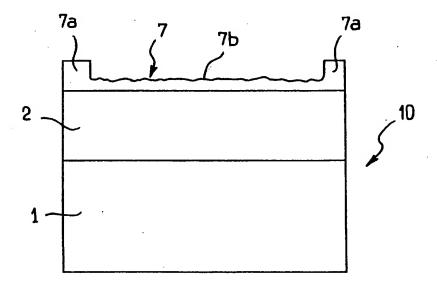


FIG.2 (Prior Art)